

Docket No.: 2336-247

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
Joo Ho LEE *et al.* : Confirmation No. 2626
U.S. Patent Application No. 10/790,723 : Group Art Unit: 2826
Filed: March 3, 2004 : Examiner: Fetsum Abraham

For: WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING
METHOD THEREOF

AMENDMENT

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria VA 22313-1450

Sir:

The following amendments and remarks are submitted in response to the Official Action
dated *March 27, 2006*.